

## ENGLISH ABSTRACT FOR TW-311269

1 / 1 WPAT - \*The Thomson Corp. - image

Accession Nbr :

1996-414711 [42]

Sec. Acc. Non-CPI :

N1996-349084

Title :

Light-emitting diode or photodiode semiconductor component with light-permeable plastic packaging - has un-metallised portions of surface covered with micro-teeth for contacting encapsulant, which has been sprayed on, compressed and hardened

Derwent Classes :

U11 U12

Patent Assignee :

(SIEI ) SIEMENS AG

Inventor(s) :

BRUNNER H

Nbr of Patents :

7

Nbr of Countries :

11

Patent Number :

EP-732740 A2 19960918 DW1996-42 H01L-023/29 Ger 6p \*

AP: 1996EP-0103346 19960304

DSR: DE FI FR GB IE IT SE

DE19509262 A1 19960919 DW1996-43 H01L-023/28 4p

AP: 1995DE-1009262 19950315

JP08264683 A 19961011 DW1996-51 H01L-023/28 4p

AP: 1996JP-0083046 19960313

TW-311269 A 19970721 DW1997-44 H01L-023/28

AP: 1996TW-0102976 19960312

CN1138216 A 19961218 DW1998-06 H01L-023/28

AP: 1996CN-0108017 19960315

US5742098 A 19980421 DW1998-23 H01L-023/04 4p

AP: 1996US-0616319 19960315

DE19509262 C2 20011129 DW2001-73 H01L-023/28

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H01L-023/04 H01L-023/28 H01L-023/29 H01L-021/56 H01L-023/31 H01L-033/00 H05K-005/00

Abstract :

EP-732740 A

The semiconductor body (2), located on one connecting finger (1) of a system carrier, has metallic contacts (3,4) on its underside and topside, formed e.g. of Aluminium or alloy or other non-noble metal.

The un-metallised surface areas are etched or otherwise treated to produce micro-teeth (5) for better contact with a transport block (8) of e.g. epoxy resin which covers the semiconductor body and metallic

contacts, the gold wire bond (6) and parts of the connecting fingers (1,7).

**USE/ADVANTAGE** - For light-emitting diodes and photodetector chips. Adhesion between semiconductor body and plastic encapsulant is improved without recourse to thermal expansion coefft. matching, surface plasma activation or interlaying. (Dwg.1/1)

**Manual Codes :**

EPI: U11-D01A1 U12-A01A4 U12-A02B3

**Update Basic :**

1996-42

**Update Equivalents :**

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**Update Equivalents (Monthly) :**

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